



# HM64

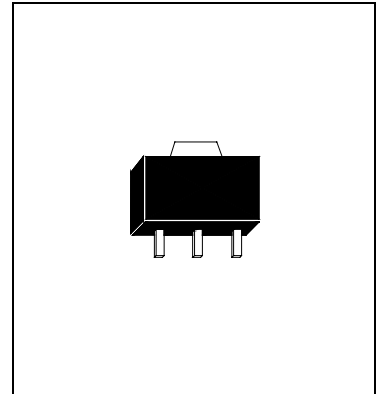
PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HM64 is a darlington amplifier transistor designed for applications requiring extremely high current gain.

## Features

- High D.C current gain
- HM64 is complementary to HM14



## Absolute Maximum Ratings

- Maximum Temperatures  
 Storage Temperature ..... -55 ~ +150 °C  
 Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
 Total Power Dissipation (Ta=25°C) ..... 1 W
- Maximum Voltages and Currents (Ta=25°C)  
 VCBO Collector to Base Voltage ..... -30 V  
 VCES Collector to Emitter Voltage ..... -30 V  
 VEBO Emitter to Base Voltage ..... -10 V  
 IC Collector Current ..... -300 mA

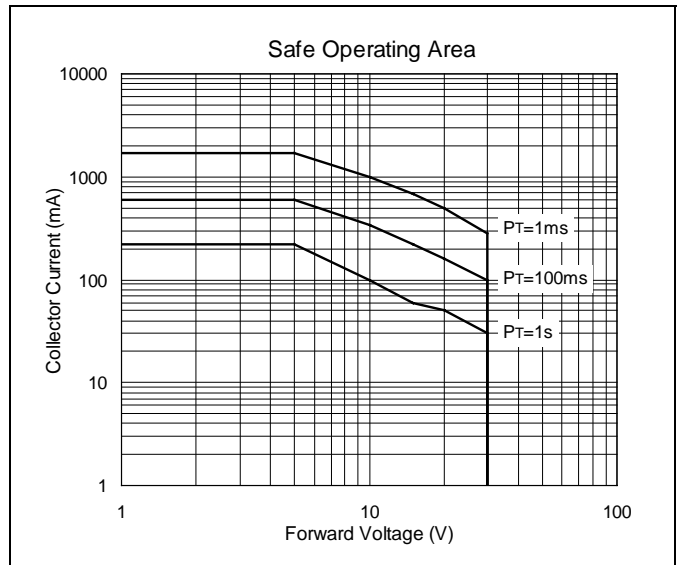
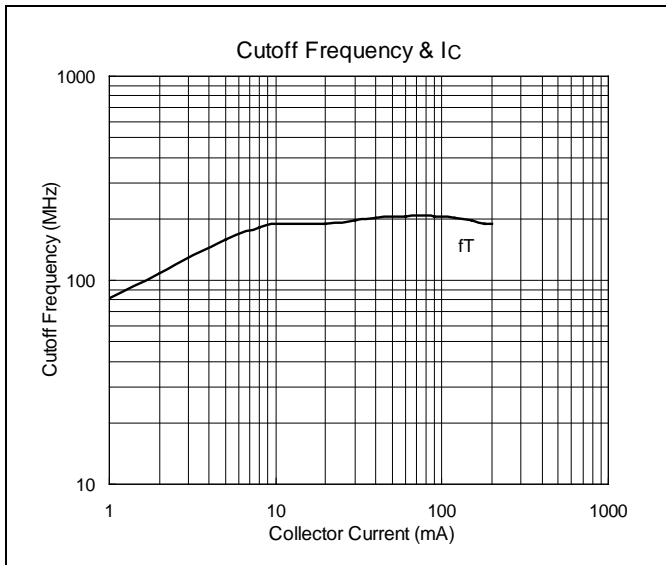
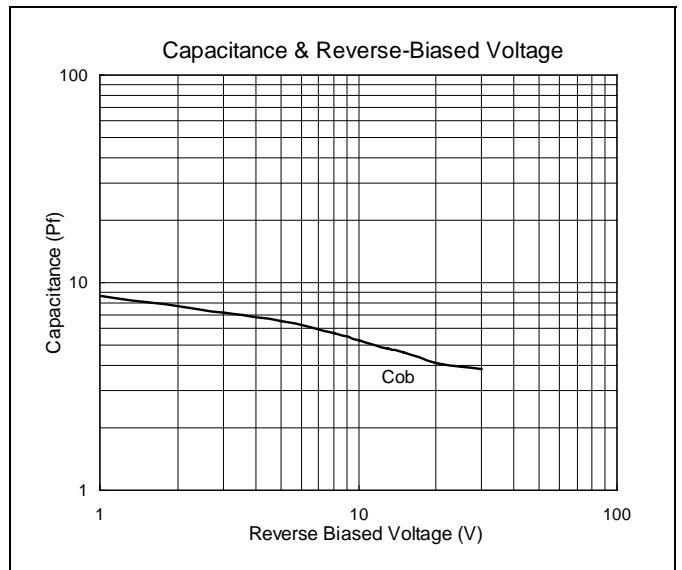
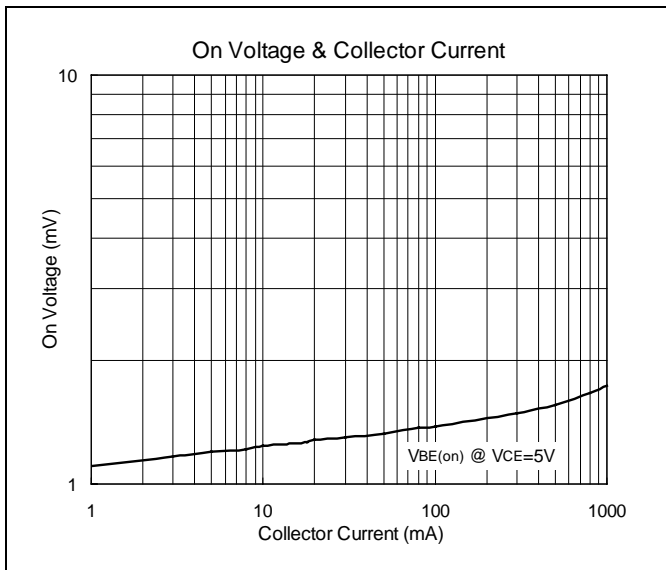
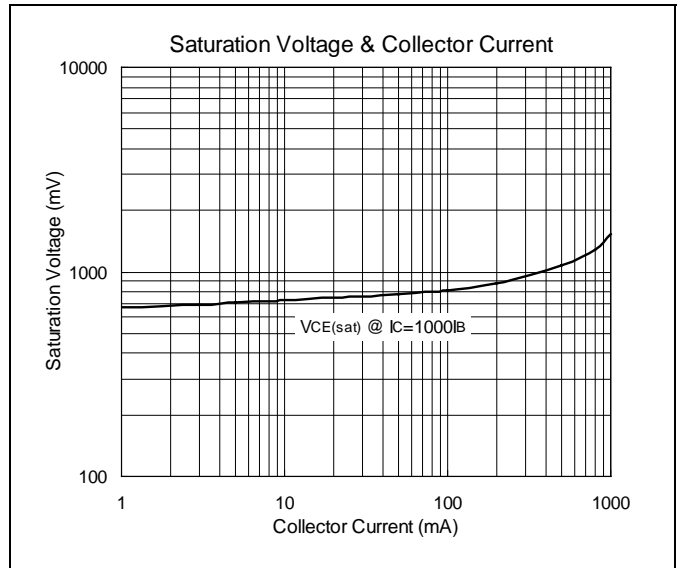
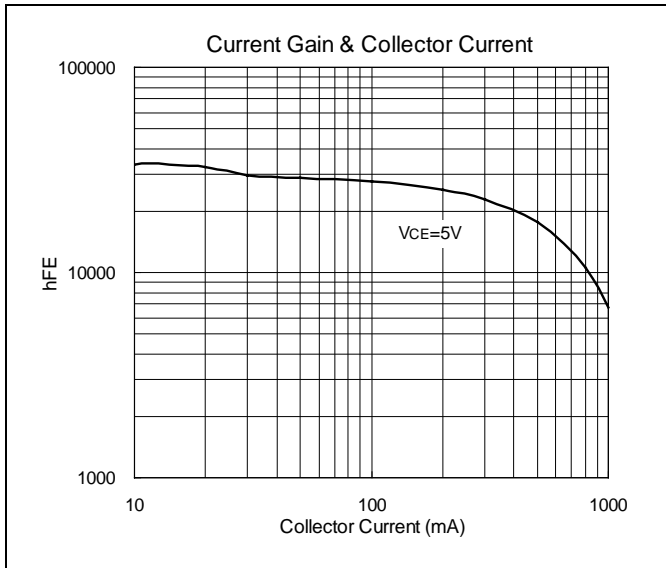
## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-30	-	-	V	IC=-100uA
BVCES	-30	-	-	V	IC=-100uA
BVEBO	-10	-	-	V	IE=-10uA
ICBO	-	-	-100	nA	VCB=-30V
IEBO	-	-	-100	nA	VEB=-10V
*VCE(sat)	-	-	-1.5	V	IC=-100mA, IB=-0.1mA
*VBE(on)	-	-	-2	V	VCE=-5V, IC=-100mA
*hFE1	10	-	-	K	VCE=-5V, IC=-10mA
*hFE2	20	-	-	K	VCE=-5V, IC=-100mA
fT	125	-	-	MHz	VCE=-5V, IC=-10mA

\*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

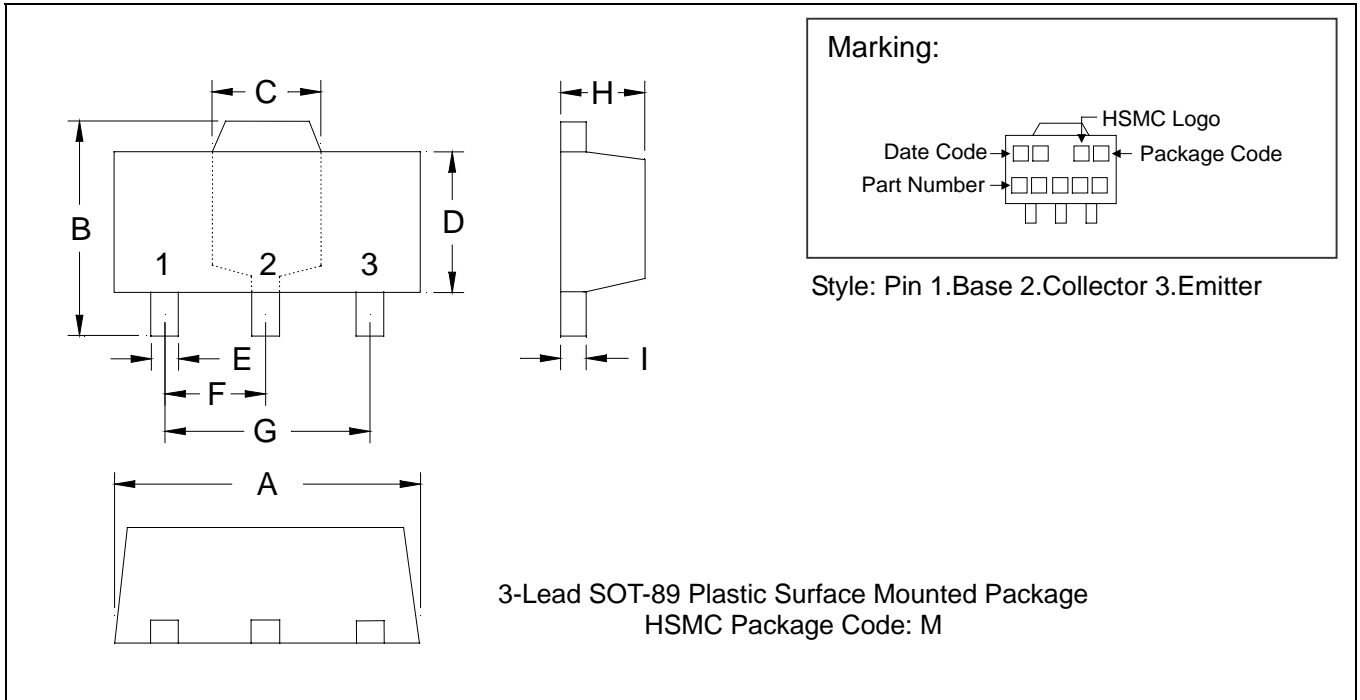


### Characteristics Curve





### SOT-89 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

**Notes:** 1.Dimension and tolerance based on our Spec. dated May. 05,1996.  
 2.Controlling dimension: millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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